INTEGRATED CIRCUITS

DATA SHEET

74F1779

8-bit bidirectional binary counter (-State)

Product specification IC15 Data Handbook





8-bit bidirectional binary counter (3-State)

74F1779

FEATURES

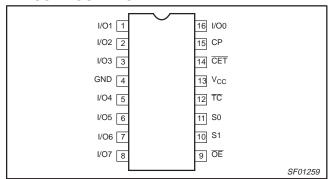
- Multiplexed 3-State I/O ports for bus oriented applications
- Built-in look-ahead carry capability
- Center power pins to reduce effects of package inductance
- Count frequency 145MHz typical
- Supply current 90mA typical
- See 74F269 for 24-pin separate I/O port version
- See 74F579 for 20-pin version
- See 74F779 for 16-pin version with abbreviated function table

DESCRIPTION

The 74F1779 is a fully synchronous 8-stage up/down counter with multiplexed 3-State I/O ports for bus-oriented applications. All control functions (hold, count up, count down, synchronous load) are controlled by two mode pins (S0, S1). The device also features carry look-ahead for easy cascading. All state changes are initiated by the rising edge of the clock. When CET is High, the data outputs are held in their current state and TC is held High. the TC output is not recommended for use as a clock or asynchronous reset due to the possibility of decoding spikes.

The 74F1779 differs from 74F779 in that it has an additional hold mode as described in the Function Table.

PIN CONFIGURATION



TYPE	TYPICAL f _{MAX}	TYPICAL SUPPLY CURRENT (TOTAL)
74F1779	130MHz	100mA

ORDERING INFORMATION

DESCRIPTION	COMMERCIAL RANGE V_{CC} = 5V $\pm 10\%$, T_{amb} = 0°C to +70°C	PACKAGE DRAWING NUMBER		
16-pin Plastic DIP	N74F1779N	SOT38-4		
16-pin Plastic SOL	N74F1779D	SOT162-1		

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

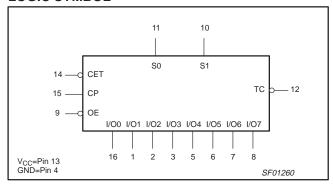
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW		
I/On	Data inputs	3.5/1.0	70μA/0.6mA		
I/OII	Data outputs	150/40	3.0mA/24mA		
S0, S1	Select inputs	1.0/1.0	20μA/0.6mA		
ŌĒ	Output Enable input (active Low)	1.0/1.0	20μA/0.6mA		
CET	CET Count Enable Trickle input (active Low)		20μA/0.6mA		
СР	Clock input (active rising edge)		20μA/0.6mA		
TC	Terminal Count output (active Low)	50/33	1.0mA/20mA		

NOTE: One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

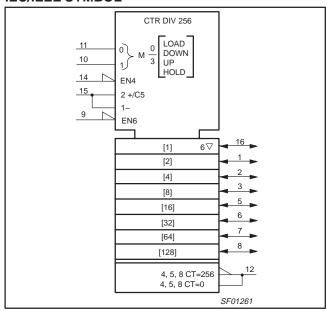
8-bit bidirectional binary counter (3-State)

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LOGIC SYMBOL



IEC/IEEE SYMBOL



FUNCTION TABLE

	ı	INPUTS	3		OPERATING MODE
S1	S0	CET	ΟE	СР	OPERATING MODE
Х	Х	Х	Н	Χ	I/O0 to I/O7 in High impedance
Х	Х	Х	L	Χ	Flip-flop outputs appear on I/O lines
L	L	Х	Н	\uparrow	Parallel load all flip-flops
(not	LL)	Н	Χ	\uparrow	Hold (TC held High)
Н	Н	Х	Χ	\uparrow	Hold
Н	L	L	Χ	1	Count up
L	Н	L	Χ	\uparrow	Count down

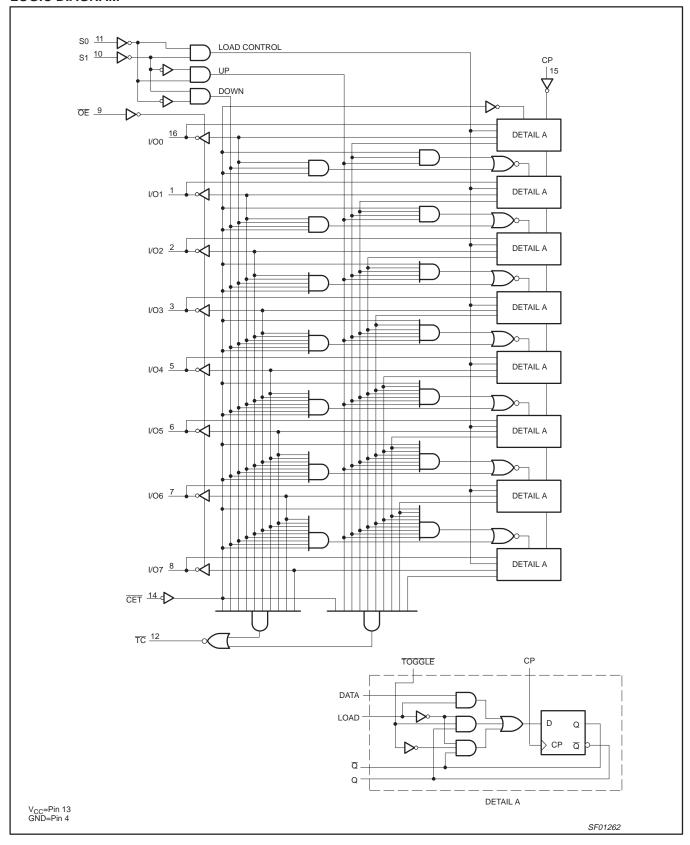
H = High voltage level

L = Low voltage level
X = Don't care

1 = Low-to-High clock transition

(not LL) = S0 and S1 should never be Low voltage level at the same time in the hold mode only.

LOGIC DIAGRAM



8-bit bidirectional binary counter (3-State)

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ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V _{CC}	Supply voltage	-0.5 to +7.0	V	
V _{IN}	Input voltage	-0.5 to +7.0	V	
I _{IN}	Input current	-30 to +5	mA	
V _{OUT}	Voltage applied to output in High output state	–0.5 to V _{CC}	V	
1	Comment and its data contains in Language and added	TC	40	mA
lout	Current applied to output in Low output state	I/On	48	mA
T _{amb}	Operating free-air temperature range	0 to +70	°C	
T _{stg}	Storage temperature		-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

SYMBOL	DADAMETER		LIMITS					
STWIDOL	PARAMETER	MIN	NOM	MAX	UNIT			
V _{CC}	Supply voltage	4.5	5.0	5.5	V			
V _{IH}	High-level input voltage	2.0			V			
V _{IL}	Low-level input voltage			0.8	V			
I _{IK}	Input clamp current			-18	mA			
	High level comment	TC			-1	mA		
Іон	High-level output current			-3	mA			
		TC			20	mA		
loL	Low-level output current	1		24	mA			
T _{amb}	Operating free-air temperature range	Operating free-air temperature range				°C		

8-bit bidirectional binary counter (3-State)

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DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

OVMDOL	DADAMETED		TOT CONDITIO	N101		LIMITS		UNIT		
SYMBOL	PARAMETER		"	TEST CONDITIONS ¹				MAX	UNIT	
		TC	$V_{CC} = MIN,$	Ι 4 στο Λ	±10%V _{CC}	2.5			V	
	I Pale Javania autoritaria de la con-	TC	$V_{IL} = MAX$ $V_{IH} = MIN$	$I_{OH} = -1 \text{mA}$	±5%V _{CC}	2.7	3.4		V	
V _{OH}	High-level output voltage	1/0	V _{CC} = MIN,	J 0A	±10%V _{CC}	2.4			V	
		I/On	$V_{IL} = MAX$ $V_{IH} = MIN$	$I_{OH} = -3mA$	±5%V _{CC}	2.7	3.3		V	
	I am land and a day to all a sec		V _{CC} = MIN,	I MANY	±10%V _{CC}		0.30	0.50	V	
V _{OL}	Low-level output voltage		$V_{IL} = MAX$ $V_{IH} = MIN$	$I_{OL} = MAX$	±5%V _{CC}		0.35	0.50	V	
V _{IK}	Input clamp voltage		V _{CC} = MIN, I	ı = I _{IK}			-0.73	-1.2	V	
	Input current at maximum	I/On	V _{CC} = 5.5V, \	V _{CC} = 5.5V, V _I = 5.5V				1	mA	
1	input voltage	others	V _{CC} = 5.5V, \			100	μΑ			
I _{IH}	High-level input current	except	$V_{CC} = MAX$,	V _I = 2.7V				20	μΑ	
I _{IL}	Low-level input current	I/On	V _{CC} = MAX,	V _I = 0.5V				-0.6	mA	
I _{IH} +I _{OZH}	Off-state output current High-level voltage applied	1/00	V _{CC} = MAX,	V _O = 2.7V				70	μΑ	
I _{IL} +I _{OZL}	Off-state output current Low-level voltage applied	I/On	V _{CC} = MAX,	$V_{CC} = MAX, V_O = 0.5V$				-600	μΑ	
I _{OS}	Short-circuit output current ³		$V_{CC} = MAX$	V _{CC} = MAX				-150	mA	
		I _{CCH}					100	145	mA	
I _{CC}	Supply current (total)	I _{CCL}	V _{CC} = MAX				100	145	mA	
		I _{CCZ}	1 1				110	155	mA	

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITION	V.	_{mb} = +25 _{CC} = +5.0 0pF, R _L =	V	T _{amb} = 0°C V _{CC} = +5. C _L = 50pF,	UNIT	
			MIN	TYP	MAX	MIN	MAX	
f _{MAX}	Maximum clock frequency	Waveform 1	115	130		100		MHz
t _{PLH} t _{PHL}	Propagation delay CP to I/On	Waveform 1	4.0 5.0	6.5 7.0	10.0 10.5	4.0 5.0	10.5 11.0	ns
t _{PLH} t _{PHL}	Propagation delay CP to TC	Waveform 1	4.0 4.5	6.5 6.5	9.0 9.0	3.5 4.0	9.5 9.5	ns
t _{PLH} t _{PHL}	Propagation delay CET to TC	Waveform 2	2.0 2.5	4.0 4.5	6.5 7.0	2.0 2.5	7.5 7.5	ns
t _{PZH} t _{PZL}	Output Enable time to High or Low level	Waveform 4 Waveform 5	2.0 4.5	4.0 6.5	6.5 9.0	2.0 4.0	7.5 9.5	ns
t _{PHZ} t _{PLZ}	Output Enable time from High or Low level	Waveform 4 Waveform 5	1.0 1.0	3.0 4.0	6.0 7.0	1.0 1.0	6.5 7.5	ns

All typical values are at V_{CC} = 5V. T_{amb} = 25°C.
 Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

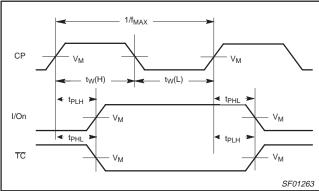
AC SETUP REQUIREMENTS

				LIMITS						
SYMBOL	PARAMETER	TEST CONDITION	T_{amb} = +25°C V_{CC} = +5.0V C_L = 50pF, R_L = 500 Ω			T _{amb} = 0°0 V _{CC} = +5. C _L = 50pF,	UNIT			
			MIN	TYP	MAX	MIN	MAX			
t _s (H) t _s (L)	Setup time, High or Low I/O _n to CP	Waveform 3	4.0 3.5			4.5 3.5		ns		
t _h (H) t _h (L)	Hold time, High or Low I/O _n to CP	Waveform 3	0 0			0 0		ns		
t _S (H) t _S (L)	Setup time, High or Low CET to CP	Waveform 3	4.5 7.0			5.0 8.0		ns		
t _h (H) t _h (L)	Hold time, High or Low CET to CP	Waveform 3	0 0			0 0		ns		
t _s (H) t _s (L)	Setup time, High or Low Sn to CP	Waveform 3	7.5 8.5			8.0 9.5		ns		
t _h (H) t _h (L)	Hold time, High or Low Sn to CP	Waveform 3	0 0			0		ns		
t _w (H) t _w (L)	CP Pulse width, High or Low	Waveform 1	3.0 4.5			3.0 5.5		ns		

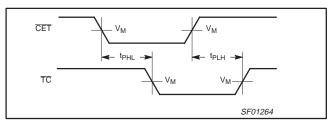
AC WAVEFORMS

For all waveforms, $V_M = 1.5V$.

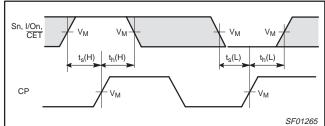
The shaded areas indicate when the input is permitted to change for predictable output performance.



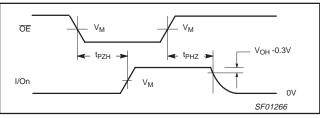
Waveform 1. Propagation Delay, Clock Input to Output, Clock Pulse Width, and Maximum Clock Frequency



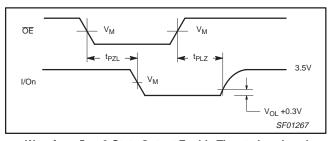
Waveform 2. Propagation Delay, CET Input to Terminal Count Output



Waveform 3. Data Setup and Hold Times



Waveform 4. 3-State Output Enable Time to High Level and Output Disable Time from High Level

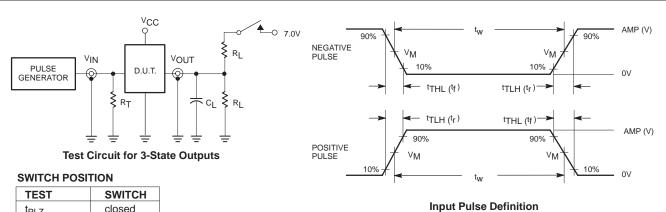


Waveform 5. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

8-bit bidirectional binary counter (3-State)

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TEST CIRCUIT AND WAVEFORMS



TEST	SWITCH
t _{PLZ}	closed
t _{PZL}	closed
All other	open

DEFINITIONS:

R_L = Load resistor;

see AC electrical characteristics for value.

C_L = Load capacitance includes jig and probe capacitance;

see AC electrical characteristics for value.

 R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

family	INP	INPUT PULSE REQUIREMENTS											
	amplitude	V_{M}	rep. rate	t _w	t _{TLH}	t _{THL}							
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns							

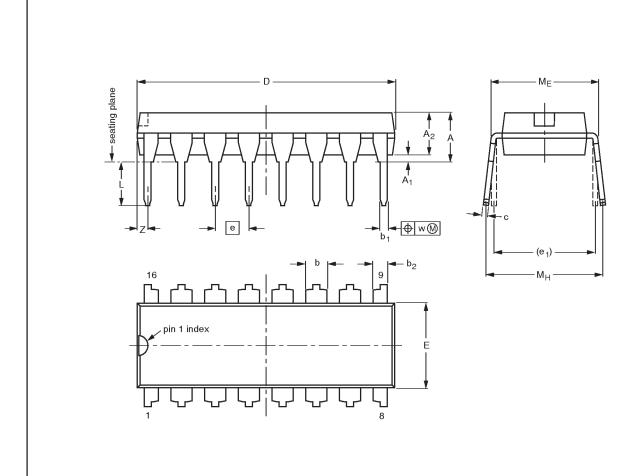
SF00777

8-bit bidirectional binary counter (3-State)

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DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	b ₂	C	D ⁽¹⁾	E ⁽¹⁾	е	e ₁	L	ME	Мн	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.030

scale

10 mm

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

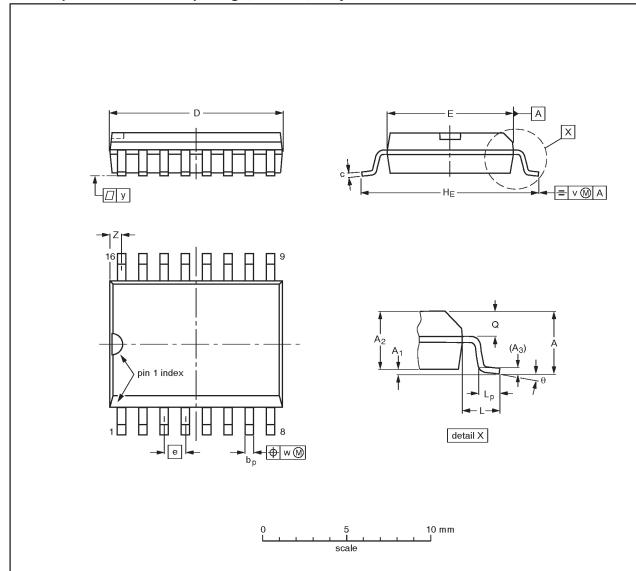
OUTLINE			EUROPEAN	ISSUE DATE			
VERSION	IEC	IEC JEDEC EIAJ				ISSUE DATE	
SOT38-4					□ •	92-11-17 95-01-14	

8-bit bidirectional binary counter (3-State)

74F1779

SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	А3	bp	С	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	Ø	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT162-1	075E03	MS-013AA				-92-11-17 95-01-24	

8-bit bidirectional binary counter (3-State)

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NOTES

8-bit bidirectional binary counter (3-State)

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DEFINITIONS						
Data Sheet Identification	Product Status	Definition				
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.				
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Phillips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.				
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